



- ☐ Drafts
- ☐ Pending
- ☒ Active
 - L1: (367) interconnect\$3 and
 - L2: (272) 1 and substrate\$1
 - L3: (30) 2 and depres\$4
 - L5: (364088) 4 insulat\$3
 - L6: (6) 4 and insulat\$3 and
 - L4: (27) 3 and conductive ar
 - L7: (439) fabricat\$3 and int
 - L8: (0) 7 and insulta\$3 and
 - L9: (225) 7 and insulat\$3 ar
 - L10: (205) 9 and layer\$1
 - L11: (173) 10 and substrate\$
 - L12: (120) 11 and cover\$3
 - L13: (120) 12 and conduct\$3
 - L14: (78) 13 and die\$1
 - L15: (13) 14 and depres\$4
 - L16: (57) "5634267"
- ☐ Failed
 - (0) 3 and conductive and lay
- ☐ Saved
- ☐ Favorites
- ☐ Tagged
- ☐ UDC
- ☐ Queue
- ☐ Trash

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DBs USPAT

☐ Plurals ☐ Synonyms

Default operator: OR

☐ Highlight all hit terms initially

"5634267"

BRS form IS&R form Image Text

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6232153 B1	20010515	13	Plastic package assembly method for a	438/127	438/112 ; 438/3
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6229324 B1	20010508	11	Test system with mechanical alignment for semiconductor	324/758	324/755 ; 324/765
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6222379 B1	20010424	15	Conventionally sized temporary package for	324/755	324/765
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6219908 B1	20010424	17	Method and apparatus for manufacturing known good	29/833	29/832 ; 324/755
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6215322 B1	20010410	14	Conventionally sized temporary package for	324/755	324/765
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6211960 B1	20010403	15	Method and apparatus for aligning and connecting	356/400	356/401
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6210984 B1	20010403	29	Method and apparatus for automatically positioning	438/15	438/10 ; 438/12
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6208157 B1	20010327	11	Method for testing semiconductor components	324/755	324/765
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6188232 B1	20010213	14	Temporary package, system, and method for testing	324/755	324/765
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6179198 B1	20010130	12	Method of soldering bumped work by partially	228/180.22	228/103
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6171164 B1	20010109	9	Method for forming uniform sharp tips for use in a	445/50	

Hits Details